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By: 

Date: January 6, 2003

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Barbara Vasquez et al.
Applic. No. : 10/062,942
Filed : January 31, 2002
Title : Method of Applying a Bottom Surface
Protective Coating to a Wafer, and Wafer
Dicing Method
Examiner : Angel Roman
Group Art Unit : 2812

A M E N D M E N T

Hon. Commissioner of Patents and Trademarks,
Washington, D. C. 20231

Sir:

Responsive to the Office action dated October 7, 2002, kindly
amend the above-identified application as follows:

In the Claims:

B¹
Claim 1 (Twice Amended). A method of applying a protective
coating to a bottom surface of a wafer, and of protecting
bottom edges and corners of chips forming part of the wafer,
which comprises the steps of:

forming trenches in a top surface of the wafer;

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